

NI/CU DOUBLE-SIDED CONDUCTIVE FABRIC TAPE

Laird Technologies' DN50A double-sided conductive nonwoven fabric tape is constructed of 15 mil (0.38 mm) nickel/copper metallized fabric with conductive pressure sensitive adhesives (PSA) on both sides. This reliable tape provides XYZ-axis electrical conductivity and EMI shielding performance.

DN50A is RoHS compliant and halogen free. It's good for EMI/RFI shielding to electronic devices.

FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Shielding effectiveness of >90 dB across a wide spectrum of frequencies

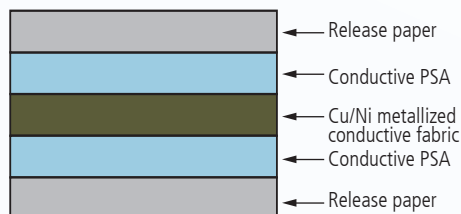
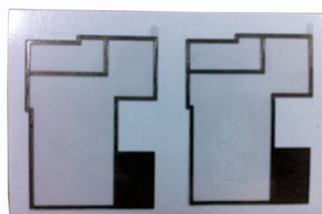
MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

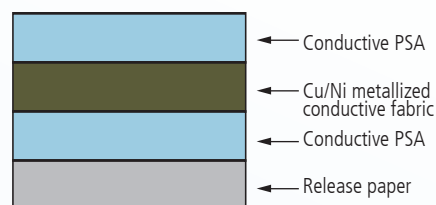


COMPOSITION OF PRODUCT

Die Cut



Roll Form



USA: +1.866.928.8181
Europe: +49.0.8031.2460.0
Asia: +86.755.2714.1166



DN50A Double-Sided Nickel/Copper Fabric Tape

Item	Unit	Typical Value	Test Method
Thickness	mm	0.50 ± 0.06	-
Peel Adhesion	Kgf / 25 mm	>1.3	PSTC 101*
Shear Adhesion at R.T.	Hrs	>24	PSTC 107#
Tensile Strength	Kgf / 25 mm	>6	
Operation Temperature	°C	0-80	-
Z-axial Resistance	Ω	<0.1	-
Far-field Shielding *			IEEE-299 (modified)
30 MHz to 300 MHz	dB	98 average	
300 MHz to 3 GHz	dB	105 average	
3 GHz to 18 GHz	dB	93 average	
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		One Year	
*: Test Method C, Dwell Time 30 Minutes		#: Contact area 25 mm by 25 mm	+: Typical Value

APPLICATION TECHNIQUES

1. Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
2. To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
3. Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.

EMI-DS-FOF-DN50A 0414

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